

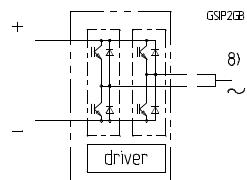
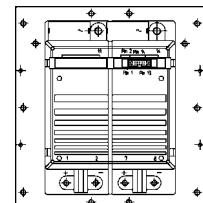
SKiiP 462 GB 060 - 250 WT

SKiiPPACK®
SK integrated
intelligent Power PACK
halfbridge

**SKiiP 462 GB 060
+ Driver 250 WT⁷⁾**

Preliminary Data

Case S2



GSP2GB

8)

Absolute Maximum Ratings		Values	Units
Symbol	Conditions ¹⁾		
IGBT & Inverse Diode			
V _{CES}		600	V
V _{CC} ¹⁰⁾	Operating DC link voltage	400	V
I _C	T _{heatsink} = 25 °C	400	A
I _{CM}	T _{heatsink} = 25 °C, t _p < 1 ms	800	A
T _j ³⁾	IGBT & Diode	- 40 ... + 150	°C
V _{isol} ⁴⁾	AC, 1 min.	2500	V
I _F	T _{heatsink} = 25 °C	400	A
I _{FM}	T _{heatsink} = 25 °C; t _p < 1 ms	800	A
I _{FSM}	t _p = 10 ms; sin.; T _j = 150 °C	4300	A
I _{FT} ²⁾ (Diode)	t _p = 10 ms; T _j = 150 °C	93	kA ² s
Driver			
V _{S1}	Stabilized power supply	18	V
V _{S2} ⁹⁾	Nonstabilized power supply	30	V
dV/dt	Primary to second. side	75	kV/μs
T _{op} , T _{stq}	Operating / stor. temperature	- 25 ... + 85	°C

Characteristics		min.	typ.	max.	Units
Symbol	Conditions ¹⁾				
V _{(BR)CES}	Driver without power supply	≥ V _{CES}	-	-	V
I _{CES}	V _{GE} = 0 { T _j = 25 °C } V _{CE} = V _{CES} { T _j = 125 °C }	-	0,6	-	mA
V _{CEsat}	I _C = 300 A { T _j = 25 (125) °C }	-	2,1(2,0)	-	V
V _{CEsat}	I _C = 400 A { T _j = 25 (125) °C }	-	2,3(2,4)	-	V
I _{CETRIP}	T _j = 125 °C, V _S = 15 V ± 0,6 V	≥ 500	-	-	A
C _{CHC}	per SKiiPPACK AC side	-	1,6	-	nF
L _{CE}	Top (Bottom)	-	7,5	-	nH
t _{d(on)}	I _C = 400 A T _j = 125 °C inductive load V _{CC} = 300 V	-	120	-	ns
t _{d(on)Driver}		-	1,2	-	μs
t _r		-	200	-	ns
t _{d(off)}		-	0,4	-	μs
t _{d(off)Driver}		-	1,2	-	μs
t _f		-	850	-	ns
E _{on} + E _{off}	V _{CC} = 300 / 400 V	-	66/92	-	mJ
Inverse Diode ²⁾					
V _F = V _{EC}	I _F = 300 A { T _j = 25 (125) °C }	-	1,5(1,5)	-	V
	I _F = 400 A { T _j = 25 (125) °C }	-	1,7(1,7)	-	V
E _{on} + E _{off}	I _F = 400 A; T _j = 125 °C	-	12	-	mJ
IGBT / Inverse Diode ²⁾					
V _{TO}	T _j = 125 °C	-	0,9/0,74	-	V
r _T	T _j = 125 °C	-	3,6/2,5	-	mΩ
Thermal Characteristics					
R _{thjh}	per IGBT	-	0,12	-	K/W
R _{thjh}	per diode	-	0,2	-	K/W
T _{tp} ¹²⁾	Over temperature protection	109	115	121	°C
R _{thha} ⁶⁾	P16/200 F; v _{air} = 293 m ³ / h	-	0,044	-	K/W
Mechanical Data					
Mdc	for DC terminals, SI Units	4	-	6	Nm
Mac	for AC terminals, SI Units	8	-	10	Nm
Case			S2		

Features

- Low thermal impedance
- Optimal thermal management with integrated heatsink
- Pressure contact technology with increased power cycling capability, compact design
- Low stray inductance
- High power, small losses
- Overtemp. protection
- Short circuit protection
- Isolated power supply

¹⁾ T_{heatsink} = 25 °C, unless otherwise specified

²⁾ CAL = Controlled Axial Lifetime Technology (soft and fast) without driver

³⁾ Driver input to DC link/AC output or DC link/AC output to heatsink⁶⁾ other heatsink on request

⁴⁾ W - Driver wire input T - Temperature protection

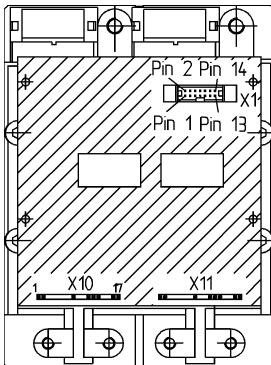
⁵⁾ AC connection busbars must be connected by user, copper busbars available on request

⁶⁾ 24 V supply voltage selective

¹¹⁾ with SK-DC link (low inductance) thermal reference for R_{thjh}; R_{thha}

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Preliminary Driver Data



Features

- CMOS compatible inputs
- Short circuit protection by V_{CE} monitoring and soft switch off
- Drive interlock top/bottom
- Isolation by transformers
- Supply undervoltage protection
- Overtemperature protection

¹⁾ 24 V - supply voltage selective

²⁾ Open collector output, external pull-up resistor necessary

³⁾ W - Driver wire input
T - Temperature protection

SKiiP 462 GB 060 - 250 WT

Driver for Halfbridge

Absolute Maximum Ratings		Values	Units	remark
Symbol	Conditions			
V_{S1}	supply voltage primary	18	V	pin 8 / 9
V_{S2} ¹⁾	supply voltage primary	30	V	pin 6 / 7
I_{outmax}	output peak current max.	± 10	A	
I_{outAV}	output average current	± 100	mA	
f_{swmax}	switching frequency max.	20	kHz	
V_{CE}	collector emitter voltage sense across IGBT	600	V	
dv/dt	rate of rise and fall of voltage (secondary to primary side)	75	kV/ μ s	
$V_{isol\ IO}$	Isol. test volt. IN/OUT (RMS; 1 min)	2,5	kV~	
$V_{isol\ 12}$	Isol. test volt. output 1 - output 2	1,5	kV=	
T_{op}, T_{stg}	operating / stor. temperature	- 25 ... + 85	°C	

Characteristics

Symbol	Conditions	Values	Units	remark
V_{S1} ¹⁾	supply voltage primary	$15,0 \pm 4\%$	V	pin 8 / 9
V_{S2}	supply voltage primary	24,0 $+25\%/-15\%$	V	pin 6 / 7
V_{UVS}	supply voltage monitoring	13 / 19,5	V	15 V / 24 V
I_{S01}	sup.current pr.side (standby)	160	mA	15 V supply
I_{S02} ¹⁾	sup.current pr.side (standby)	125	mA	24 V supply
I_{S1}	sup. current pr.side (max)	490	mA	15 V supply
I_{S2} ¹⁾	sup. current pr.side (max)	380	mA	24 V supply
V_{IT+}	input thresh. volt. (high) min	12,9	V	
V_{IT-}	input thresh. volt. (low) max.	2,1	V	
$V_{GE(on)}$	turn-on output gate voltage	15	V	
$V_{GE(off)}$	turn-off output gate voltage	- 8	V	
$t_{d(on)}$	propagation delay time on	1,2	μ s	typ.
$t_{d(off)}$	propagation delay time off	1,2	μ s	typ.
t_{TD}	dead time of interlock	3	μ s	typ.
V_{CEstat}	V_{ce} -thresh. st. monitoring	3,2	V	typ.
V_{ol} ²⁾	logic low output voltage	< 600	mV	15 mA
V_{oh} ²⁾	logic high output voltage	max. 30	V	
$t_{pdon-error}$	propag. delay time-on error	6	μ s	typ.
$t_p RESET$	min. pulse width error memory RESET	5	μ s	
T_{err}	max. temperature	115 ± 6	°C	
I_{AOmax}	max. output current	± 5	mA	pin 12